



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-05-18
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	8ZH*TWB151K	A	64BA	2017-05-18
Amount	UoM	Unit type	ST ECOPACK Grade	
250.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	6.69-5.63-2.38	2	J bend	
Comment	Package: SMC CLIP (SOD 15) - MD valid for CPs: SMCJ130CA-TR - SM15T150CA			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.80	die backside metal - leadframe metal	3200
Lead	4.25	soft solder	17012

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	8ZH*TWB151K					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	4.999	mg	supplier	die	Silicon (Si)	7440-21-3		4.909	mg	981996	19636
				supplier	metallization	Aluminium (Al)	7429-90-5		0.014	mg	2801	56
				supplier	Passivation	Silicon Oxide	7631-86-9		0.019	mg	3801	76
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.019	mg	3801	76
				supplier	back side metallization	Gold (Au)	7440-57-5		0.007	mg	1400	28
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.031	mg	6201	124
Leadframe	Copper & its alloys	79.539	mg	supplier	alloy	Copper (Cu)	7440-50-8		78.691	mg	989339	314764
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.079	mg	993	316
				supplier	metallization	Nickel (Ni)	7440-02-0		0.769	mg	9668	3076
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	4.253	mg	955086	17012
Soft solder	Solder	4.453	mg	supplier	solder	Silver (Ag)	7440-22-4		0.111	mg	24927	444
				supplier	solder	Tin (Sn)	7440-31-5		0.089	mg	19987	356
				supplier	solder	Tin (Sn)	7440-31-5		0.089	mg	19987	356
Encapsulation	Other Organic Materials	119.523	mg	supplier	mold compound	Amorphous Silica	7631-86-9		87.370	mg	730989	349480
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		22.709	mg	189997	90836
				supplier	mold compound	Phenol resin	9003-35-4		3.586	mg	30003	14344
				supplier	mold compound	Bisphenol A-bisphenol A diglycidyle ether poly	25036-25-3		3.586	mg	30003	14344
				supplier	mold compound	Carbon black	1333-86-4		1.076	mg	9001	4304
				supplier	mold compound	Triphenylphophine	603-35-0		0.837	mg	7003	3348
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.359	mg	3004	1436
Connections coating	Solder	1.972	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.972	mg	1000000	7888
Clip	Copper & its alloys	39.514	mg	supplier	alloy	Copper (Cu)	7440-50-8		39.514	mg	1000000	158056